2SC5440

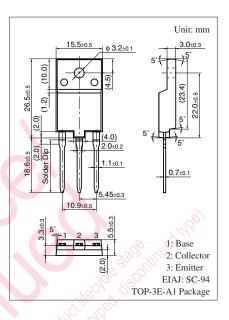
Silicon NPN triple diffusion mesa type

For horizontal deflection output

Features

- High breakdown voltage, and high reliability through the use of a glass passivation layer
- High-speed switching
- Wide safe operation area (ASO)

Absolute Maximum Ratings $T_C = 25^{\circ}C$ Parameter Symbol Unit Rating Collector-base voltage (Emitter open) 1500 V V_{CBO} Collector-emitter voltage (E-B short) V_{CES} 1500 V V Collector-emitter voltage (Base open) 600 VCEO 7 Emitter-base voltage (Collector open) V VEBO Base current 7.5 I_B А 15 Collector current I_C А 25 Peak collector current * ICP A Collector power dissipation W P_C 60 $T_a = 25^{\circ}C$ 3.0 °C Junction temperature Ti 150 Storage temperature -55 to +150 °C T_{stg}



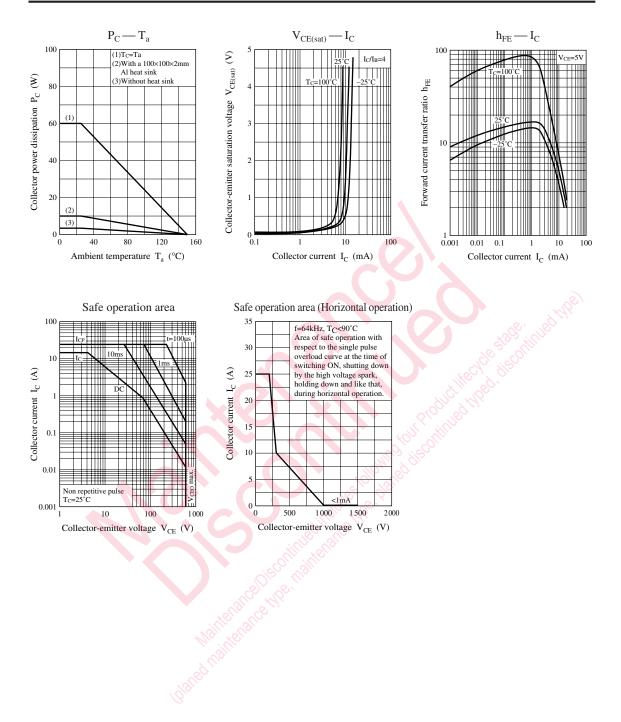
Note) *: Non-repetitive peak collector current

Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 1000$ V, $I_E = 0$			50	μΑ
	Tor al	$V_{CB} = 1500 \text{ V}, I_E = 0$			1	mA
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 7 V, I_C = 0$			50	μΑ
Forward current transfer ratio	h _{FE}	$V_{CE} = 5 V, I_C = 7.5 A$	5		9	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = 7.5 \text{ A}, I_{\rm B} = 1.88 \text{ A}$			3	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_C = 7.5 \text{ A}, I_B = 1.88 \text{ A}$			1.5	V
Transition frequency	f _T	$V_{CE} = 10 \text{ V}, I_C = 0.1 \text{ A}, f = 0.5 \text{ MHz}$		3		MHz
Storage time	t _{stg}	$I_C = 7.5 \text{ A}$, Resistance loaded			2.7	μs
Fall time	t _f	$I_{B1} = 1.88 \text{ A}, I_{B2} = -3.76 \text{ A}$			0.2	μs

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

Panasonic



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